



# First Call For Papers

## 2021 IEEE 14<sup>th</sup> International Conference on ASIC

Oct. 26-29, 2021, Wyndham-Grand Plaza Royale Hotel  
Kunming, China

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**2021 IEEE 14<sup>th</sup> International Conference on ASIC (ASICON 2021)** will be held in Kunming, China, during Oct.26-29, 2021. The conference is intended to provide an international forum for Integrated circuit designers, ASIC users, system integrators, IC manufacturers, process and device engineers, and CAD/CAE tool developers to present their latest progress, development and research results in their respective fields. The four-day event features keynote speeches, invited talks, regular paper presentations and tutorials, delivered by leading experts in the respective fields, on state-of-the-art Integrated circuits, design methodologies, devices, processes and manufacturing technologies. The Excellent Student Paper Award & Excellent Young Scholar Paper Award will be announced at the conference. Additionally, an exhibition on EDA tools, foundry technologies, IC processing/testing facilities, and novel ASIC products will be held during the conference.

### *The Scope of the Conference*

Papers are solicited in, but not limited to, the following:

#### **I. Integrated Circuits and Design Techniques**

- [1] **Analog IC**
  - Amplifiers,
  - Data converters (ADCs and DACs)
  - Power management ICs and Energy Harvesting
  - Clock generator,
- [2] **Digital IC**
  - Low power technique
  - CPU, MCU, GPU, Embedded processors and DSP
  - Machine learning IC
  - Chaos/neural/fuzzy-logic circuits
  - Programmable devices (PLD, EPLD, HDPLD, FPGA, etc)
  - NOC
- [3] **Wireless, Wireline telecommunication and Optic Communication IC**
  - RF block circuits (LNA, Mixer, PA, Integrated Antenna and Switches),
  - RF Transceiver (Transmitter, receiver, PLL in RF transceiver), RFID
  - millimeter-wave circuits
  - Seders
  - THz circuits,
  - Laser Driver, TIA, CDR,
- [4] **Memory**
  - DRAM & SRAM
  - Flash memory
  - Ferroelectric memory
  - Phase change memory, RRAM, MRAM
  - Novel memory
- [5] **Sensor, Image Processing and Bio-medical IC**
  - Sensor circuits
  - Graph theory and computing
  - Biomedical circuits and systems
  - Wearable systems

